

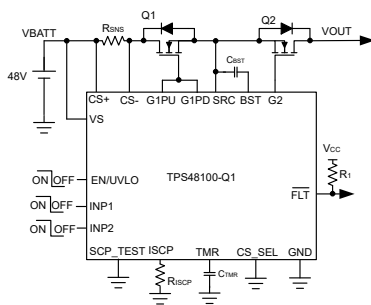
TPS4810-Q1 100V Automotive Low I_Q, Back-to-Back MOSFET Smart High Side Driver With Short-Circuit Protection and Diagnostics

1 Features

- AEC-Q100 automotive qualified for automotive applications
 - Device temperature grade 1: –40°C to +125°C ambient operating temperature range
- **Functional Safety-Capable**
 - [Documentation available to aid functional safety system design](#)
- 3.5V to 95V input range (100V absolute maximum)
- Reverse input protection down to –65V
- Integrated 11V charge pump with 345µA capacity
- Low quiescent current, 35µA in operation
- Low 1.5µA shutdown current (EN/UVLO = Low)
- Two strong gate drivers (2A source and sink) for back to back MOSFET driving with separate control inputs (INP1, INP2)
- Adjustable short circuit protection (ISCP) using external R_{sense} or MOSFET VDS sensing with adjustable delay (TMR)
- High or low-side current sense configuration (CS_SEL)
- Fault indication ($\overline{\text{FLT}}$) during short circuit fault, charge pump undervoltage, input undervoltage, and short-circuit comparator diagnosis (SCP_TEST)
- Adjustable input undervoltage lockout (UVLO)
- Pin-to-pin compatible with [TPS1210-Q1](#)

2 Applications

- [Automotive 48V Li-ion battery management system](#)
- [DC/DC converter](#)
- [Automotive power distribution box](#)
- [Cordless power tools](#)



BMS Breaker With Separate Discharge and Charge FET Control

3 Description

The TPS48100-Q1 is a 100V low I_Q smart high side driver with protection and diagnostics. With wide operating voltage range of 3.5V–95V, the device is suitable for 12V, 24V, and 48V system designs. The device can withstand and protect the loads from negative supply voltages down to –65V.

It has two strong 2A (source and sink) gate drivers with separate control inputs (INP1, INP2) to drive back to back MOSFETs in common source configuration. Strong GATE driving enables power switching using parallel MOSFETs in high current system designs.

The device provides adjustable short-circuit protection. Auto-retry and latch-off fault behavior can be configured. Current sensing can be done either by an external sense resistor or by MOSFET VDS sensing. High side or low side current sense resistor configuration is possible by using CS_SEL pin input. The device also features diagnosis of the internal short circuit comparator using external control on SCP_TEST input.

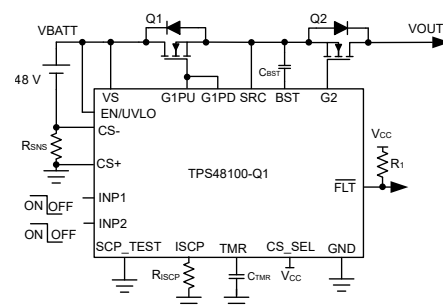
A low quiescent current (35µA, typical) in operation enables always ON system designs. Quiescent current reduces to 1.5µA (typical) with EN/UVLO low.

The TPS48100-Q1 is available in a 19-pin VSSOP package.

Package Information

PART NUMBER	PACKAGE ⁽¹⁾	PACKAGE SIZE ⁽²⁾
TPS48100-Q1	DGX (VSSOP, 19)	5.1mm × 3.0mm

- (1) For all available packages, see the orderable addendum at the end of the data sheet.
- (2) The package size (length × width) is a nominal value and includes pins, where applicable.



BMS Breaker With Low Side Current Sense



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4 Pin Configuration and Functions

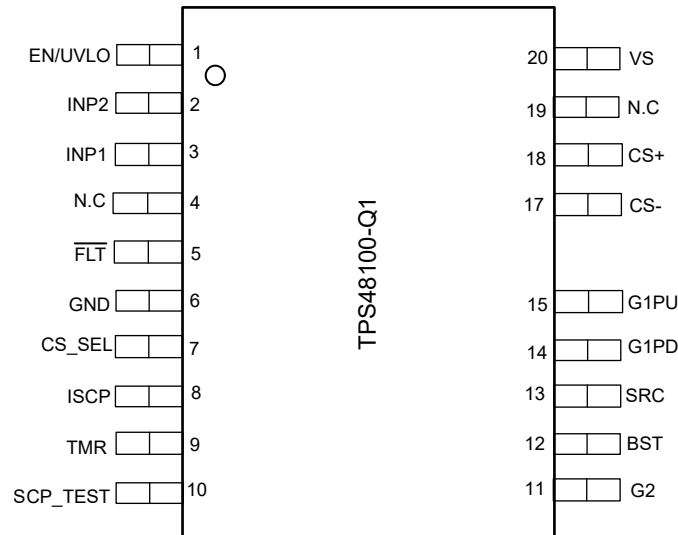


Figure 4-1. DGX Package, 19-Pin VSSOP (Top View)

Table 4-1. Pin Functions

PIN		TYPE ⁽¹⁾	DESCRIPTION
NAME	NO.		
EN/UVLO	1	I	EN/UVLO Input. A voltage on this pin above 1.24V enables normal operation. Forcing this pin below 0.3V shuts down the device reducing quiescent current to approximately 1.5µA. Optionally connect to the input supply through a resistive divider to set the undervoltage lockout. When EN/UVLO is left floating an internal pull down of 100nA pulls EN/UVLO low and keeps the device in shutdown state.
INP2	2	I	Input signal for external charge FET control. CMOS compatible input reference to GND that sets the state of G2 pin. INP2 has an internal weak pull down of 100nA to GND to keep G2 pulled to SRC when INP2 is left floating.
INP1	3	I	Input signal for external discharge FET control. CMOS compatible input reference to GND that sets the state of G1PD and G1PU pins. INP1 has an internal weak pull down of 100nA to GND to keep G1PD pulled to SRC when INP1 is left floating.
N.C	4	—	No connect.
FLT	5	O	Open drain fault output. This pin asserts low during short circuit fault, charge pump UVLO, input UVLO, and during SCP comparator diagnosis. If FLT feature is not desired then connect it to GND.
GND	6	G	Connect GND to system ground.
CS_SEL	7	I	Current sense select input. Connect this pin to ground to activate high side current sense. Drive this pin to >2V to activate low side current sensing. CS_SEL has an internal weak pull down of 100nA to GND.

Table 4-1. Pin Functions (continued)

PIN		TYPE ⁽¹⁾	DESCRIPTION
NAME	NO.		
ISCP	8	I	Short circuit detection setting. A resistor across ISCP to GND sets the short circuit current comparator threshold. If short-circuit protection feature is not desired then connect CS+, CS–, and VS pins together. Also connect ISCP and TMR pins to GND.
TMR	9	I	Fault timer input. A capacitor across TMR pin to GND sets the times for fault turn-off. Leave it open for fastest setting. Leave this pin open for fastest response setting. If short-circuit protection feature is not desired then connect CS+, CS–, and VS pins together. Also, connect ISCP and TMR pins to GND.
SCP_TEST	10	I	Internal short circuit comparator (SCP) diagnosis input. When SCP_TEST is driven low to high with INP1 pulled high, the internal SCP comparator operation is checked. \overline{FLT} goes low and G1PD gets pulled to SRC if SCP comparator is functional. Connect SCP_TEST pin to GND if this feature is not desired. SCP_TEST has an internal weak pull down of 100nA to GND.
G2	11	O	Charging FET gate drive output. It has 1.69A peak source and 2A sink capacity. Leave the G2 pin floating if the G2 drive functionality is unused.
BST	12	O	High side bootstrapped supply. An external capacitor with a minimum value of $>Q_{g(tot)}$ of the external FET must be connected between this pin and SRC.
SRC	13	O	Source connection of the external FET.
G1PD	14	O	High current gate driver pull-down. This pin pulls down to SRC. For the fastest turn-off, tie this pin directly to the gate of the external high side MOSFET.
G1PU	15	O	High current gate driver pull-up. This pin pulls up to BST. Connect this pin to G1PD for maximum gate drive transition speed. A resistor can be connected between this pin and the gate of the external MOSFET to control the in-rush current during turn-on.
CS–	17	I	Current sense negative input.
CS+	18	I	Current sense positive input.
N.C	19	—	No connect.
VS	20	P	Supply pin of the controller.

(1) I = Input, O = Output, I/O = Input and Output, P = Power, G = Ground

5 Specifications

5.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

		MIN	MAX	UNIT
Input Pins	VS, CS+, CS– to GND	–65	100	V
	SRC to GND	–65	100	
	G1PU, G1PD, G2, BST to SRC	–0.3	19	
	ISCP, TMR, SCP_TEST to GND	–0.3	5.5	
	EN/UVLO, INP1, INP2, CS_SEL, $V_{(VS)} > 0$ V	–1	70	
	EN/UVLO, INP1, INP2, CS_SEL, $V_{(VS)} \leq 0$ V	$V_{(VS)}$	$(70 + V_{(VS)})$	
	CS+ to CS–	–1	100	V
	FLT to GND	–1	20	V
Sink current	$I_{(FLT)}$		10	mA
	$I_{(CS+)}$, $I_{(CS-)}$, 1msec	–100	100	mA
Output Pins	G1PU, G1PD, G2, BST to GND	–65	112	V
Operating junction temperature, T_j ⁽²⁾		–40	150	°C
Storage temperature, T_{stg}		–55	150	

- Operation outside the Absolute Maximum Ratings may cause permanent device damage. Absolute Maximum Ratings do not imply functional operation of the device at these or any other conditions beyond those listed under Recommended Operating Conditions. If used outside the Recommended Operating Conditions but within the Absolute Maximum Ratings, the device may not be fully functional, and this may affect device reliability, functionality, performance, and shorten the device lifetime.
- High junction temperatures degrade operating lifetimes. Operating lifetime is de-rated for junction temperatures greater than 125°C.

5.2 ESD Ratings

			VALUE	UNIT	
$V_{(ESD)}$	Electrostatic discharge	Human body model (HBM), per AEC Q100-002 ⁽¹⁾	±2000	V	
		Charged device model (CDM), per AEC Q100-011	Corner pins (EN/UVLO, VS, SCP_TEST, G2)		±750
			Other pins		±500

- AEC Q100-002 indicates that HBM stressing shall be in accordance with the ANSI/ESDA/JEDEC JS-001 specification.

5.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

		MIN	NOM	MAX	UNIT
Input Pins	VS to GND	3.5		95	V
	Minimum voltage on VS pin for Short Circuit Protection	4			
	EN/UVLO, INP1, INP2, CS_SEL to GND	0		65	
Output Pins	FLT to GND	0		15	V
External Capacitor	VS, SRC to GND	22			nF
	BST to SRC	0.1			µF
T_j	Operating Junction temperature ⁽²⁾	–40		150	°C

- Recommended Operating Conditions are conditions under which the device is intended to be functional. For specifications and test conditions, see Electrical Characteristics.
- High junction temperatures degrade operating lifetimes. Operating lifetime is de-rated for junction temperatures greater than 125°C.

5.4 Thermal Information

THERMAL METRIC ⁽¹⁾		TPS4810-Q1	
		DGX	UNIT
		19 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	92.3	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	28.6	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	47.5	°C/W
Ψ_{JT}	Junction-to-top characterization parameter	0.6	°C/W
Ψ_{JB}	Junction-to-board characterization parameter	47.2	°C/W

(1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.

5.5 Electrical Characteristics

$T_J = -40\text{ }^\circ\text{C}$ to $+125\text{ }^\circ\text{C}$. $V_{(VS)} = 48\text{ V}$, $V_{(BST-SRC)} = 11\text{ V}$

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
SUPPLY VOLTAGE						
V_S	Operating input voltage		3.5		95	V
$V_{(S_PORR)}$	Input supply POR threshold, rising		1.85	2.55	3.3	V
$V_{(S_PORF)}$	Input supply POR threshold, falling		1.71	2.33	3.05	V
$I_{(Q)}$	Total System Quiescent current, $I_{(GND)}$	$V_{(EN/UVLO)} = 2\text{ V}$		35	45	μA
	Total System Quiescent current, $I_{(GND)}$	$V_{(EN/UVLO)} = 2\text{ V}$, $-40\text{ }^\circ\text{C} \leq T_J \leq +85\text{ }^\circ\text{C}$			44	μA
$I_{(SHDN)}$	SHDN current, $I_{(GND)}$	$V_{(EN/UVLO)} = 0\text{ V}$, $V_{(SRC)} = 0\text{ V}$		0.86	3.3	μA
$I_{(REV)}$	$I_{(VS)}$ leakage current during Reverse Polarity	$0\text{ V} \leq V_{(VS)} \leq -65\text{ V}$	19	22.4	37	μA
ENABLE, UNDERVOLTAGE LOCKOUT (EN/UVLO), SHORT CIRCUIT COMPARATOR TEST (SCP_TEST) INPUT						
$V_{(UVLOR)}$	UVLO threshold voltage, rising		1.176	1.23	1.287	V
$V_{(UVLOF)}$	UVLO threshold voltage, falling		1.09	1.138	1.184	V
$V_{(ENR)}$	Enable threshold voltage for low Iq shutdown, rising				1	V
$V_{(ENF)}$	Enable threshold voltage for low Iq shutdown, falling		0.3			V
$I_{(EN/UVLO)}$	Enable input leakage current	$V_{(EN/UVLO)} = 70\text{ V}$			476	nA
$V_{(SCP_TEST_H)}$	SCP test mode rising threshold				2	V
$V_{(SCP_TEST_L)}$	SCP test mode falling threshold		0.8			V
$I_{(SCP_TEST)}$	SCP_TEST input leakage current			90	700	nA
CHARGE PUMP (BST-SRC)						
$I_{(BST)}$	Charge Pump Supply current	$V_{(BST-SRC)} = 10\text{ V}$, $V_{(EN/UVLO)} = 2\text{ V}$	190	345	466	μA
$V_{(BST_UVLOR)}$	$V_{(BST-SRC)}$ UVLO voltage threshold, rising	$V_{(EN/UVLO)} = 2\text{ V}$	8.1	9	9.9	V
$V_{(BST_UVLOF)}$	$V_{(BST-SRC)}$ UVLO voltage threshold, falling	$V_{(EN/UVLO)} = 2\text{ V}$	7.31	8.2	8.9	V
$V_{(BST-SRC_ON)}$	Charge Pump Turn ON voltage	$V_{(EN/UVLO)} = 2\text{ V}$	9.3	10.3	11.4	V
$V_{(BST-SRC_OFF)}$	Charge Pump Turn OFF voltage	$V_{(EN/UVLO)} = 2\text{ V}$	10.4	11.6	12.8	V
$V_{(BST-SRC)}$	Charge Pump Voltage at $V_{(VS)} = 3.5\text{ V}$	$V_{(EN/UVLO)} = 2\text{ V}$	9.1	10.5	11.6	V
$I_{(SRC)}$	SRC pin leakage current	$V_{(EN/UVLO)} = 2\text{ V}$, $V_{(INP1)} = V_{(INP2)} = 0\text{ V}$		0.85	1	μA
GATE DRIVER OUTPUTS (G1PU, G1PD, G2)						
$V_{(G1_GOOD)}$	G1 Good rising threshold		5.5	7	8.3	V
$I_{(G1PU)}$	Peak Source Current			1.69		A
$I_{(G1PD)}$	Peak Sink Current			2		A

5.5 Electrical Characteristics (continued)

$T_J = -40\text{ }^\circ\text{C}$ to $+125\text{ }^\circ\text{C}$. $V_{(VS)} = 48\text{ V}$, $V_{(BST - SRC)} = 11\text{ V}$

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
$I_{(G2)}$	G2 Peak Source Current			1.69		A
$I_{(G2)}$	G2 Peak Sink Current			2		A
SHORT CIRCUIT PROTECTION (ISCP)						
$I_{(SCP)}$	SCP Input Bias current		8.4	10	12.33	μA
$V_{(SCP)}$	SCP threshold	$R_{(ISCP)} = 140.5\text{ k}\Omega$		300		mV
		$R_{(ISCP)} = 28\text{ k}\Omega$	60	75	90.5	mV
		$R_{(ISCP)} = 10.5\text{ k}\Omega$	32	40	48.9	mV
		$R_{(ISCP)} = 500\ \Omega$	15	20	25	mV
		$R_{(ISCP)} = \text{Open}$			757	mV
$V_{(SCP)}$	SCP threshold with external bias voltage on ISCP pin	$V_{(ISCP)} = 1.405\text{ V}$	283	300	316	mV
		$V_{(ISCP)} = 280\text{ mV}$	68.7	75	82.5	mV
		$V_{(ISCP)} = 105\text{ mV}$	34.5	40	46.5	mV
DELAY TIMER (TMR)						
$I_{(TMR_SRC_CB)}$	TMR source current		67	87	104	μA
$I_{(TMR_SRC_FLT)}$	TMR source current		1.4	2.73	3.8	μA
$I_{(TMR_SNK)}$	TMR sink current		2.17	2.8	3.4	μA
$V_{(TMR_SC)}$			0.93	1.1	1.2	V
$V_{(TMR_LOW)}$			0.15	0.21	0.25	V
$N_{(A-R\text{ Count})}$				32		
INPUT CONTROLS (INP1, INP2), CURRENT SENSE SELECT (CS_SEL) & FAULT FLAG (FLT)						
$R_{(FLT)}$	FLT Pull-down resistance		53	83	107	Ω
$I_{(FLT)}$	FLT Input leakage current	$0\text{ V} \leq V_{(FLT)} \leq 20\text{ V}$			410	nA
$V_{(INP1_H)}, V_{(INP2_H)}$					2	V
$V_{(INP1_L)}, V_{(INP2_L)}$			0.8			V
$I_{(INP1)}, I_{(INP2)}$	INP Input leakage current			98	206	nA
$V_{(CS_SEL_H)}$	CS_SEL threshold for low side sensing				2	V
$V_{(CS_SEL_L)}$	CS_SEL threshold for high side sensing		0.8			V

5.6 Switching Characteristics

$T_J = -40\text{ }^\circ\text{C}$ to $+125\text{ }^\circ\text{C}$. $V_{(VS)} = 48\text{ V}$, $V_{(BST - SRC)} = 11\text{ V}$

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
$t_{G1PU(INP_H)}$	INP1 Turn ON propagation Delay	INP1 \uparrow to G1PU \uparrow , $C_L = 47\text{ nF}$	0.19		1.53	μs
$t_{G2(INP2_H)}$	INP2 Turn ON propagation Delay	INP2 \uparrow to G2 \uparrow , $C_L = 47\text{ nF}$	2.7	4.5	6.7	μs
$t_{G1PD(INP_L)}$	INP1 Turn OFF propagation Delay	INP1 \downarrow to G1PD \downarrow , $C_L = 47\text{ nF}$		0.29	0.85	μs
$t_{G2(INP2_L)}$	INP2 Turn OFF propagation Delay	INP2 \downarrow to G2 \downarrow , $C_L = 47\text{ nF}$	2.7	4.4	6.79	μs
$t_{PD(EN_OFF)}$	EN Turn OFF Propagation Delay	EN \downarrow to G1PD \downarrow , $C_L = 47\text{ nF}$	2.2	4.6	6	μs
$t_{PD(UVLO_OFF)}$	UVLO Turn OFF Propagation Delay	UVLO \downarrow to G1PD \downarrow and \overline{FLT} \downarrow , $C_L = 47\text{ nF}$	2.8	4.2	6	μs
t_{SC}	Hard Short-circuit protection propagation delay	$V_{(CS+ - CS-)} \uparrow V_{(SCP)}$ to G1PD \downarrow , $C_L = 47\text{ nF}$, $C_{(TMR)} = \text{Open}$			4	μs
t_{SC_PUS}	Short-circuit protection propagation delay during power up with output short circuit	$C_{(TMR)} = \text{Open}$			10	μs

5.6 Switching Characteristics (continued)

$T_J = -40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$. $V_{(VS)} = 48\text{ V}$, $V_{(BST-SRC)} = 11\text{ V}$

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
F_{ISCP}	ISCP Pulse current frequency			1.18		kHz

5.7 Typical Characteristics

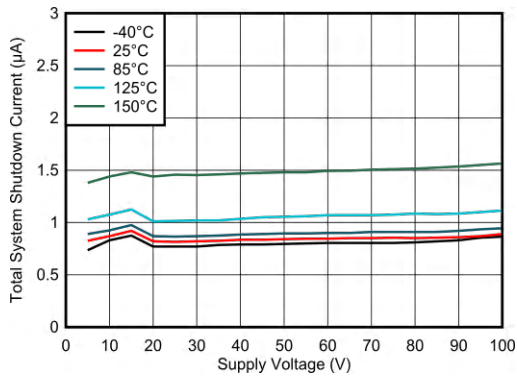


Figure 5-1. Shutdown Supply Current vs Supply Voltage

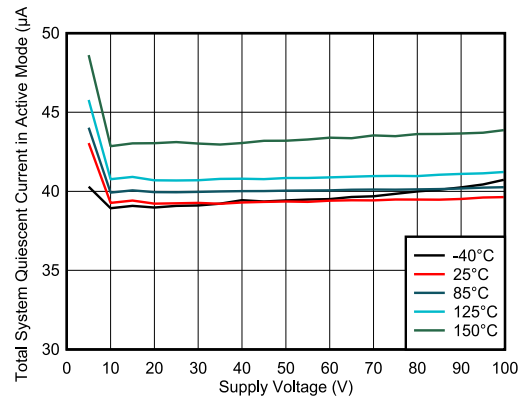


Figure 5-2. Operating Quiescent Current in Active Mode vs Supply Voltage

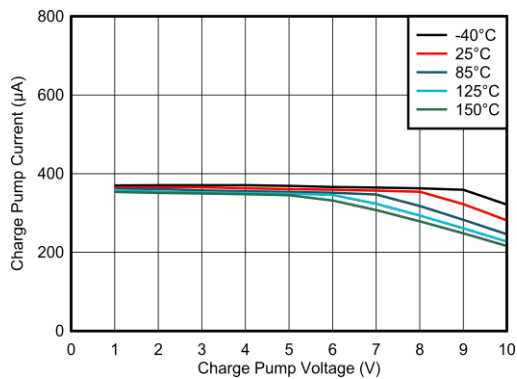


Figure 5-3. Charge Pump Current vs Charge Pump Voltage

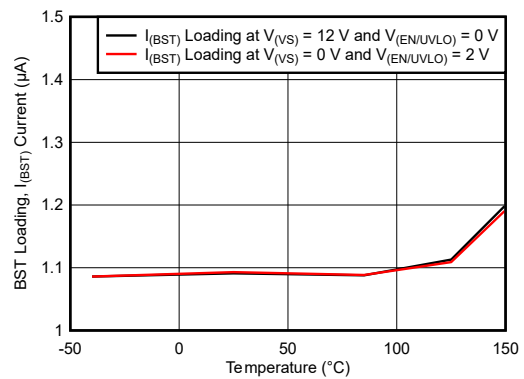


Figure 5-4. BST Loading Current (I_{BST}) vs Temperature

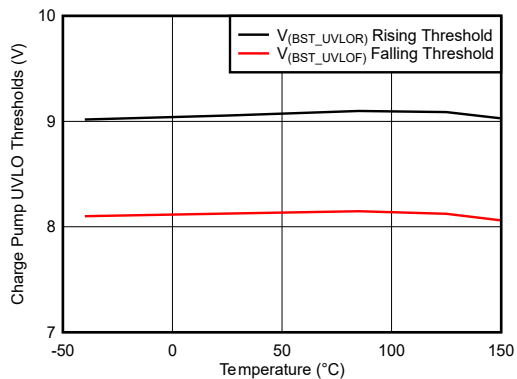


Figure 5-5. Charge Pump UVLO Thresholds vs Temperature

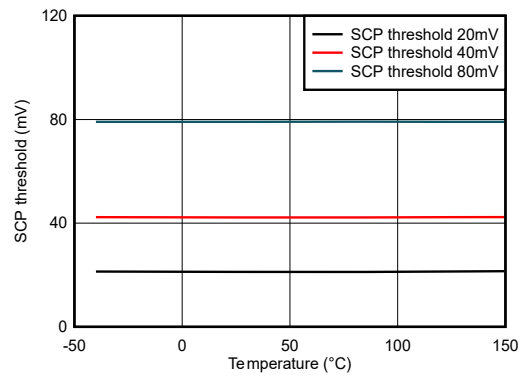


Figure 5-6. Short-Circuit Threshold (V_{SCP}) vs Temperature

5.7 Typical Characteristics (continued)

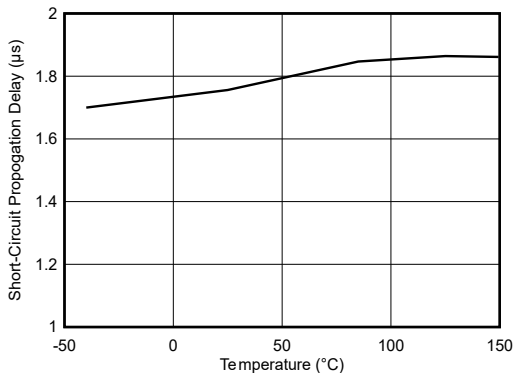


Figure 5-7. Short Circuit Protection Response Time (t_{sc}) vs Temperature

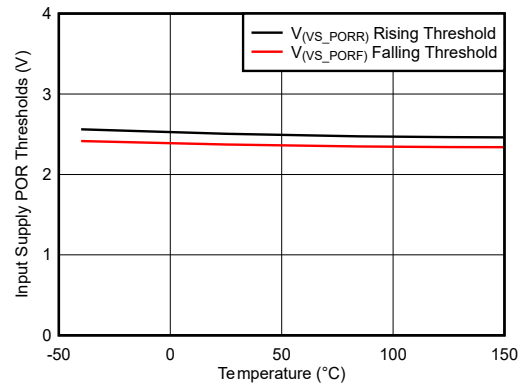


Figure 5-8. Input Supply POR Thresholds vs Temperature

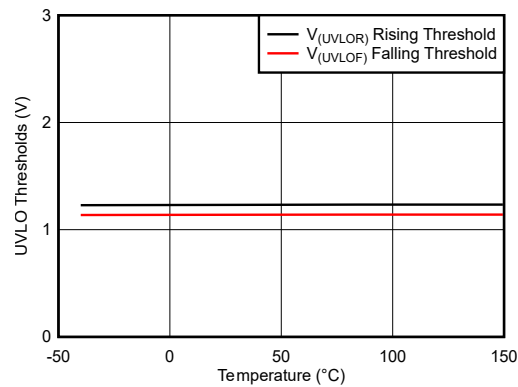


Figure 5-9. Input Supply UVLO Thresholds vs Temperature

6 Parameter Measurement Information

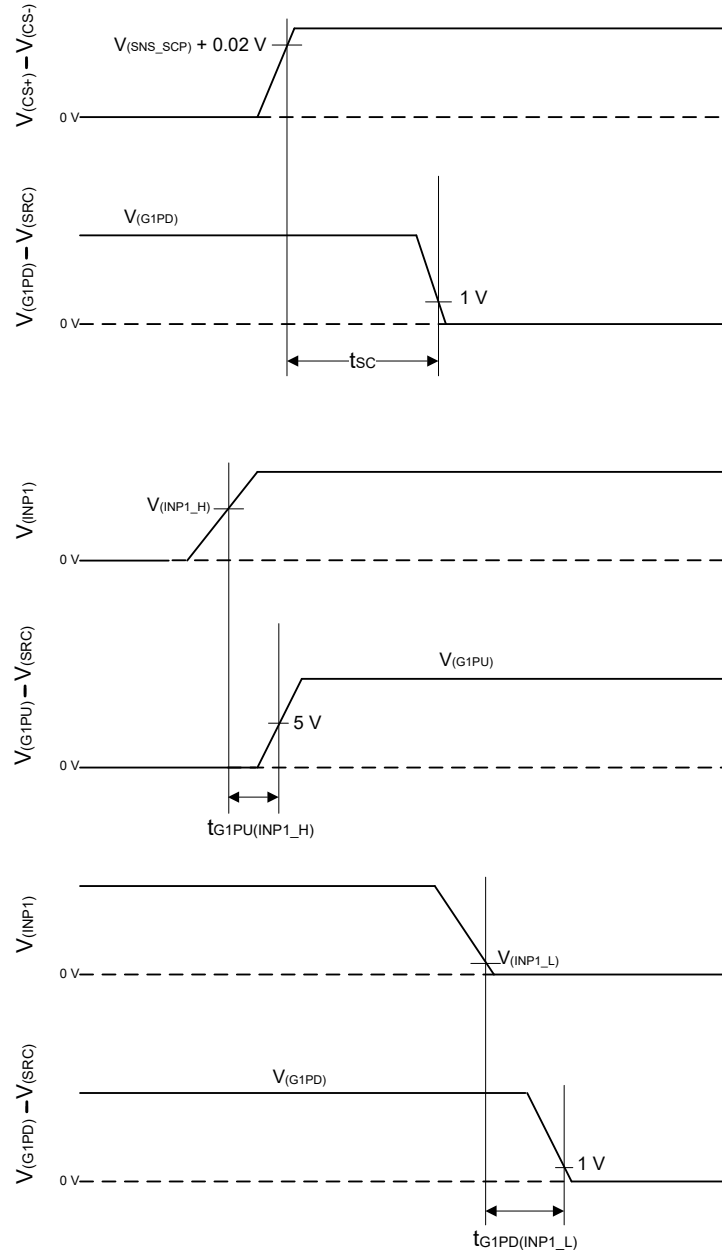


Figure 6-1. Timing Waveforms

7 Detailed Description

7.1 Overview

The TPS48100-Q1 is a 100V low IQ smart high side driver with protection and diagnostics. With wide operating voltage range of 3.5V–95V, the device is suitable for 12V, 24V, and 48V system designs. The device can withstand and protect the loads from negative supply voltages down to –65V.

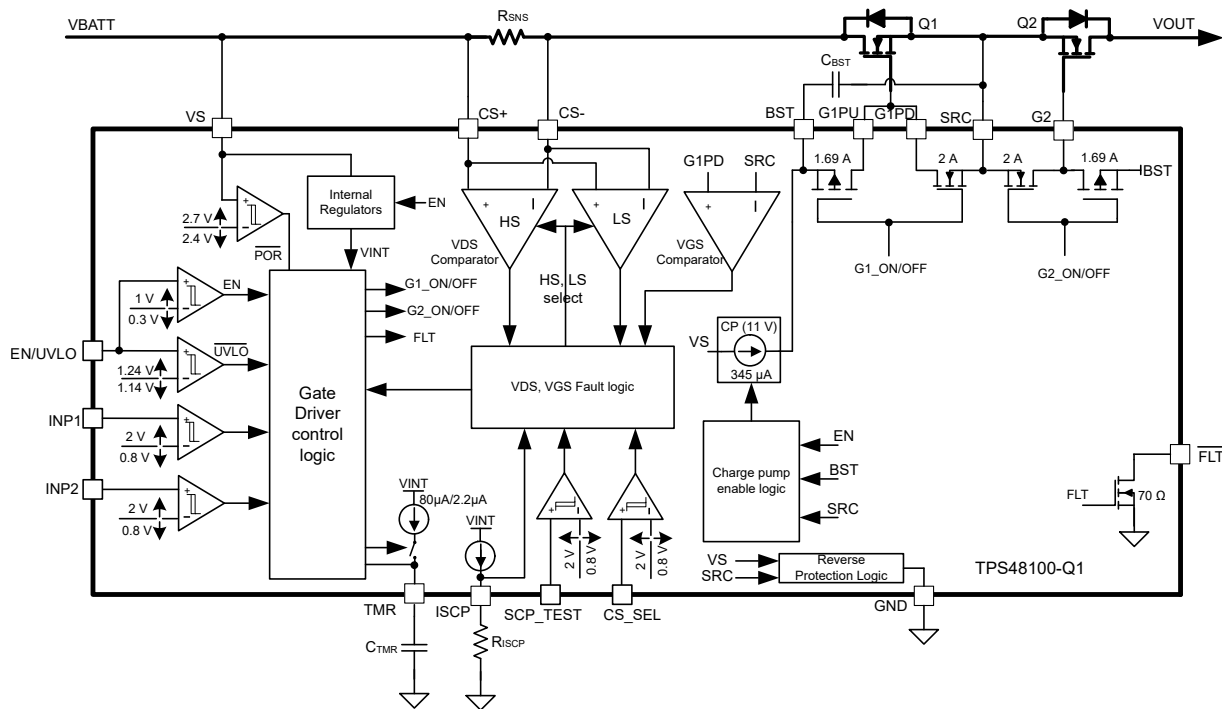
It has two strong 1.69A and 2A peak source and sink gate drivers with separate control inputs (INP1, INP2) to drive back to back MOSFETs in common source configuration. Strong GATE driving enables power switching using parallel FETs in high current system designs.

The device provides configurable short circuit protection using ISCP and TMR pins for adjusting the threshold and response time, respectively. Auto-retry and latch-off fault behavior can be configured. With TPS48100-Q1, current sensing can be done either by an external sense resistor or by MOSFET VDS sensing by using CS+ and CS– pins. High side or low side current sense resistor configuration is possible by using CS_SEL pin input. Diagnosis of the integrated short circuit comparator is possible using external control on SCP_TEST input.

The device indicates fault ($\overline{\text{FLT}}$) on open drain output during short-circuit, charge pump undervoltage, and input undervoltage conditions.

Low quiescent current 35 μA (typical) in operation enables always ON system designs. Quiescent current reduces to 1.5 μA (typical) with EN/UVLO low.

7.2 Functional Block Diagram



7.3 Feature Description

7.3.1 Charge Pump and Gate Driver Output (VS, G1PU, G1PD, G2, BST, SRC)

Figure 7-1 shows a simplified diagram of the charge pump and gate driver circuit implementation. The device houses two strong 1.69A/2A peak source/sink gate drivers enabling paralleling of FETs in high power system designs ensuring minimum transition time in saturation region. A 11V, 345µA charge pump is derived from VS terminal and charges the external boot-strap capacitor, C_{BST} that is placed across the gate driver (BST and SRC).

VS is the supply pin to the controller. With VS applied and EN/UVLO pulled high, the charge pump turns ON and charges the C_{BST} capacitor. After the voltage across C_{BST} crosses $V_{(BST_UVLOR)}$, the GATE driver section is activated. The device has a 1V (typical) UVLO hysteresis to ensure chattering less performance during initial GATE turn ON. Choose C_{BST} based on the external FET Q_G and allowed dip during FET turn-ON. The charge pump remains enabled until the BST to SRC voltage reaches 11.8V, typically, at which point the charge pump is disabled decreasing the current draw on the VS pin. The charge pump remains disabled until the BST to SRC voltage discharges to 10V typically at which point the charge pump is enabled. The voltage between BST and SRC continue to charge and discharge between 11.8V and 10V as shown in the Figure 7-2.

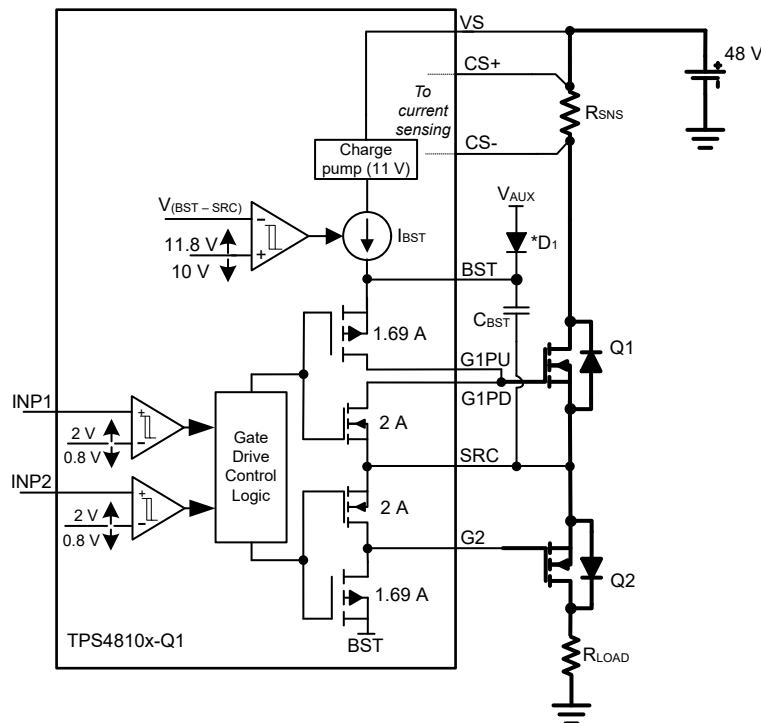


Figure 7-1. Gate Drivers

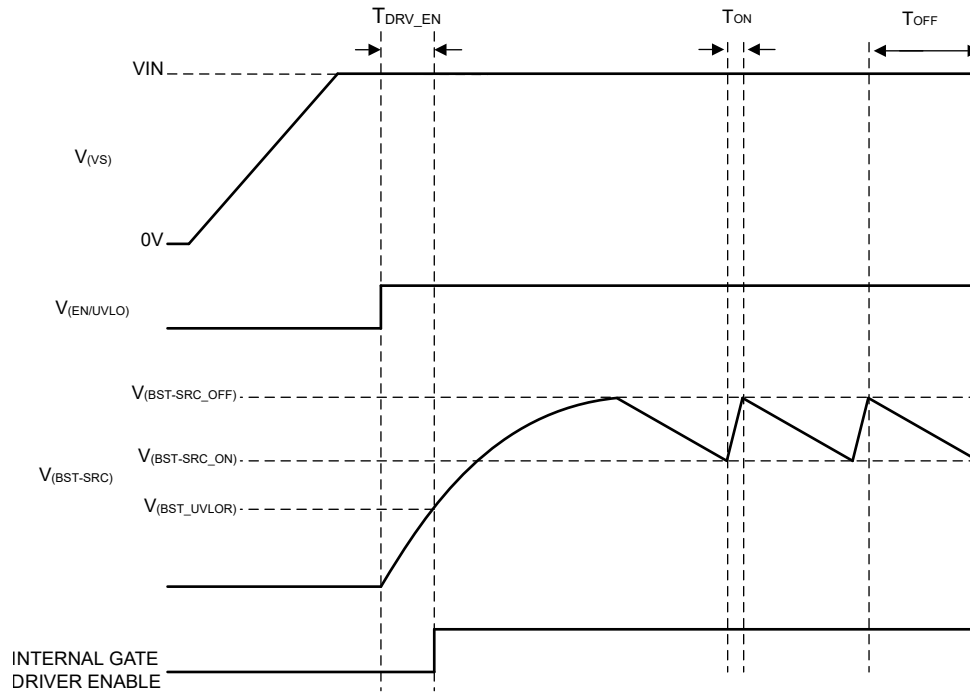


Figure 7-2. Charge Pump Operation

Use the following equation to calculate the initial gate driver enable delay:

$$T_{DRV_EN} = \frac{C_{BST} \times V_{(BST_UVLOR)}}{345 \mu A} \tag{1}$$

Where,

C_{BST} is the charge pump capacitance connected across BST and SRC pins.

$V_{(BST_UVLOR)} = 9.5V$ (max).

If T_{DRV_EN} needs to be reduced then pre-bias BST terminal externally using an external V_{AUX} supply through a low leakage diode D_1 as shown in [Figure 7-3](#). With this connection, T_{DRV_EN} reduces to 400µs. TPS48100-Q1 application circuit with external supply to BST is shown in [Figure 7-3](#).

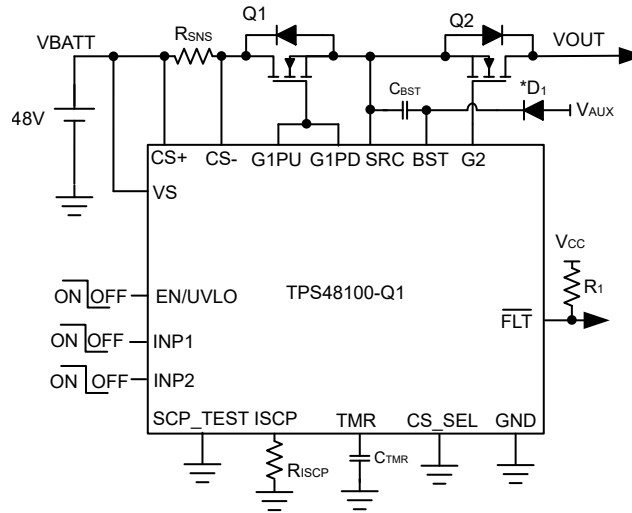


Figure 7-3. TPS4810-Q1 Application Circuit With External Supply to BST

Note

V_{AUX} can be supplied by external regulated supply ranging between 8V and 18V.

7.3.2 Capacitive Load Driving Using FET Gate (G1PU, G1PD) Slew Rate Control

For limiting inrush current during turn-ON of the external FET (Q1) with capacitive loads, use R₁, R₂, C₁ as shown in Figure 7-4. The R₁ and C₁ components slow down the voltage ramp rate at the gate of Q1 FET. The FET source follows the gate voltage resulting in a controlled voltage ramp across the output capacitors.

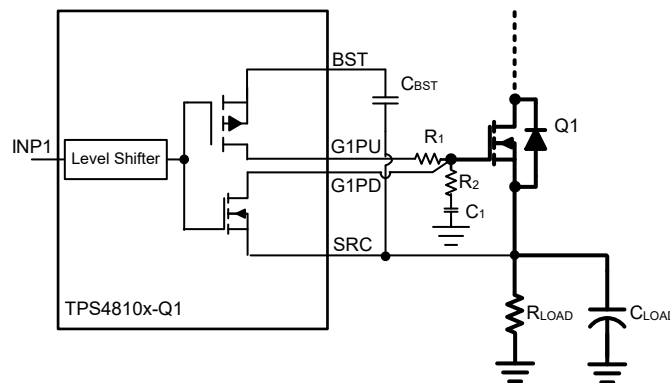


Figure 7-4. Inrush Current Limiting Using G1 Gate Drive

Use the Equation 2 to calculate the inrush current during turn-ON of the FET.

$$I_{\text{INRUSH}} = C_{\text{LOAD}} \times \frac{V_{\text{BATT}}}{T_{\text{charge}}} \quad (2)$$

$$C_1 = \frac{0.63 \times V_{(\text{BST} - \text{SRC})} \times C_{\text{LOAD}}}{R_1 \times I_{\text{INRUSH}}} \quad (3)$$

Where,

C_{LOAD} is the load capacitance.

VBATT is the input voltage and T_{charge} is the charge time.

$V_{(BST-SRC)}$ is the charge pump voltage (11V),

Use a damping resistor R_2 (approximately 10Ω) in series with C_1 . Equation 3 can be used to compute required C_1 value for a target inrush current. A $100k\Omega$ resistor for R_1 can be a good starting point for calculations.

Connecting G1PD pin of TPS48100-Q1 directly to the gate of the Q1 FET ensures fast turn-OFF without any impact of R_1 and C_1 components.

C_1 results in an additional loading on C_{BST} to charge during turn-ON. Use below equation to calculate the required C_{BST} value:

$$C_{BST} = \frac{Q_{g(total)}}{\Delta V_{BST}} + 10 \times C_1 \tag{4}$$

Where,

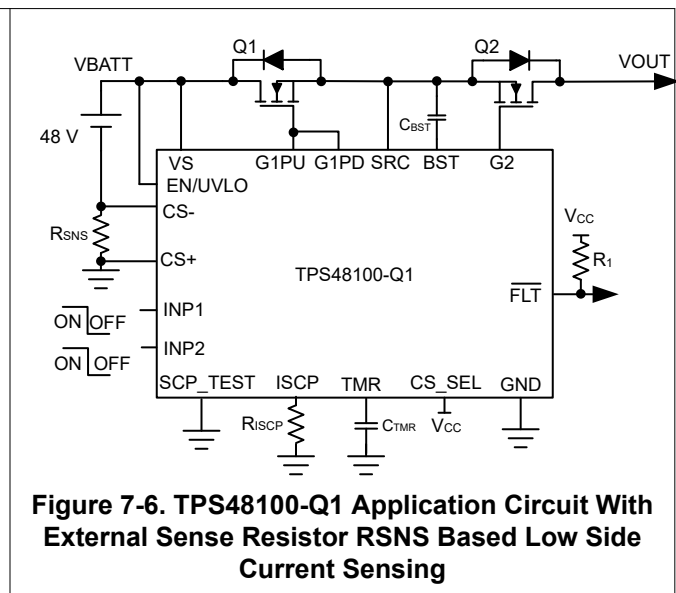
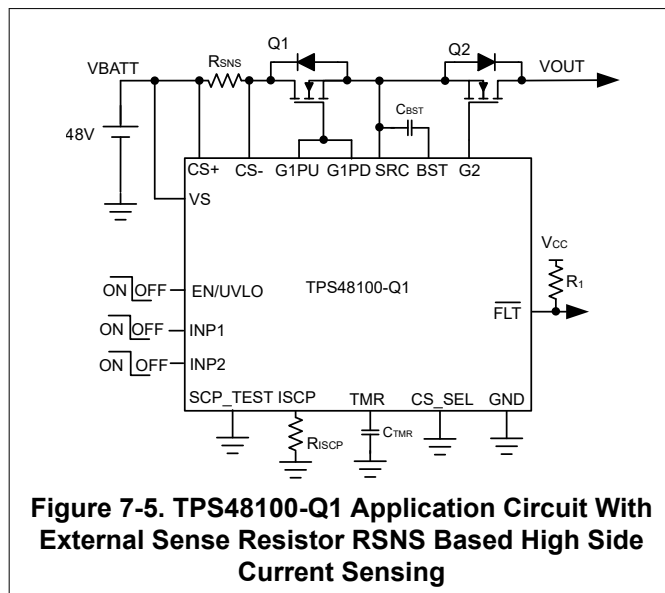
$Q_{g(total)}$ is the total gate charge of the FET,

ΔV_{BST} (1V typical) is the ripple voltage across BST to SRC pins.

7.3.3 Short-Circuit Protection

The TPS48100-Q1 feature adjustable short circuit protection. The threshold and response time can be adjusted using R_{ISCP} resistor and C_{TMR} capacitor respectively. The device senses the voltage across CS+ and CS- pins.

These pins can be connected across an external high and low side current sense resistor (R_{SNS}) or across the FET drain and source terminals for FET RDSON sensing as shown in Figure 7-5, Figure 7-6 and Figure 7-7 respectively.



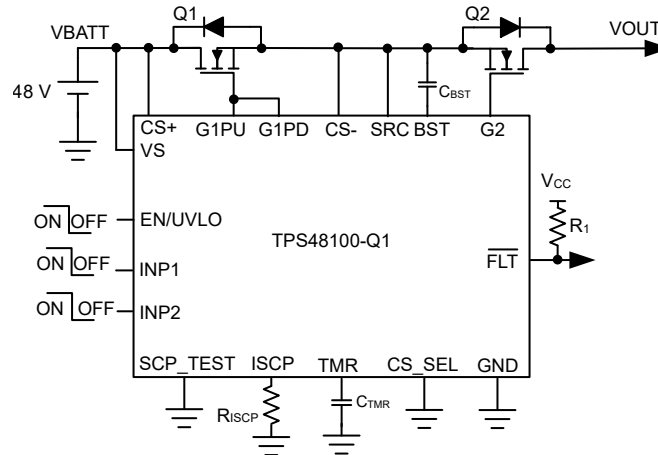


Figure 7-7. TPS4810-Q1 Application Circuit with MOSFET RDSON Based Current Sensing

Set the short-circuit detection threshold using an external R_{ISCP} resistor across ISCP and GND pins. Use Equation 5 to calculate the required R_{ISCP} value:

$$R_{ISCP} (\Omega) = \frac{(I_{SC} \times R_{SNS} - 19 \text{ mV})}{2 \mu\text{A}} \quad (5)$$

Where,

R_{SNS} is the current sense resistor value or the FET R_{DSON} value.

I_{SC} is the desired short circuit current level.

The short circuit protection response is fastest with no C_{TMR} cap connected across TMR and GND pins.

With device powered ON and EN/UVLO, INP pulled high, During Q1 turn ON, first VGS of external FET Q1 (G1 gate drive) is sensed by monitoring the voltage across G1PD to SRC. Once G1PD to SRC voltage raises above $V_{(G1_GOOD)}$ threshold which ensures that the external FET is enhanced, then the SCP comparator output is monitored. If the sensed voltage across CS+ and CS– exceeds the short-circuit set point (V_{SCP}), G1PD pulls low to SRC and \overline{FLT} asserts. Subsequent events can be set either to be auto-retry or latch off as described in following sections.

VGS of external FET (Q1) is only monitored when CS_SEL is pulled low. VGS of external FET (Q1) is not monitored for low side current sensing as shown in Figure 7-6.

Note

Short-circuit threshold can also be set by connecting external bias voltage on ISCP pin via buffer instead of R_{ISCP} resistor enabling system design with improved SCP threshold accuracy as mentioned in electrical characteristics table. The external bias voltage to be forced on ISCP pin can be calculated by below equation:

$$V_{(SCP_BIAS)} \text{ in mV} = I_{SC} \times R_{SNS} \times 5 - 95\text{mV}$$

7.3.3.1 Short-Circuit Protection With Auto-Retry

The C_{TMR} programs the short-circuit protection delay (t_{SC}) and auto-retry time (t_{RETRY}). Once the voltage across CS+ and CS– exceeds the set point, the C_{TMR} starts charging with $80\mu\text{A}$ pull-up current.

After C_{TMR} charges to $V_{(TMR_SC)}$, G1PD pulls low to SRC and \overline{FLT} asserts low providing warning on impending FET turn OFF. Post this event, the auto-retry behavior starts. The C_{TMR} capacitor starts discharging with $2.5\mu\text{A}$ pulldown current. After the voltage reaches $V_{(TMR_LOW)}$ level, the capacitor starts charging with $2.2\mu\text{A}$ pullup. After 32 charging-discharging cycles of C_{TMR} the FET turns ON back and \overline{FLT} de-asserts.

The device retry time (t_{RETRY}) is based on C_{TMR} for the first time as per Equation 7 .

Use Equation 6 to calculate the C_{TMR} capacitor to be connected across TMR and GND.

$$C_{TMR} = \frac{I_{TMR} \times t_{SC}}{1.1} \tag{6}$$

Where,

I_{TMR} is internal pull-up current of 80 μ A.

t_{SC} is desired short-circuit response time.

The fastest t_{SC} is with no C_{TMR} cap connected.

$$t_{RETRY} = 22.7 \times 10^6 \times C_{TMR} \tag{7}$$

If the short-circuit pulse duration is below t_{SC} then the FET remains ON and C_{TMR} gets discharged using internal pull down switch.

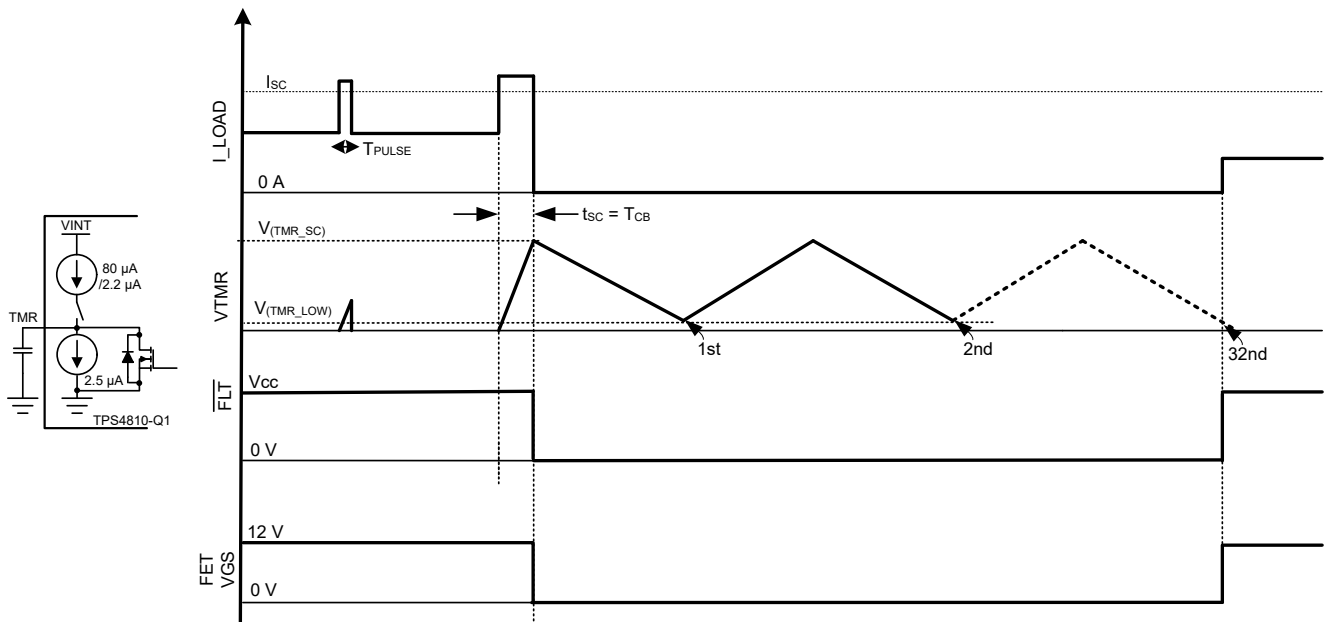


Figure 7-8. Short-Circuit Protection With Auto-Retry

7.3.3.2 Short-Circuit Protection With Latch-Off

Connect an approximately 100k Ω resistor across C_{TMR} as shown in Figure 7-9. With this resistor, during the charging cycle, the voltage across C_{TMR} gets clamped to a level below $V_{(TMR_SC)}$ resulting in a latch-off behavior and \overline{FLT} asserts low at same time.

Use Equation 8 to calculate C_{TMR} capacitor to be connected between TMR and GND for $R_{TMR} = 100k\Omega$.

$$C_{TMR} = \frac{t_{SC}}{R_{TMR} \times \ln\left(\frac{1}{1 - \frac{1.1}{R_{TMR} \times 80 \mu A}}\right)} \tag{8}$$

Where,

I_{TMR} is internal pull-up current of $80\mu A$.

t_{SC} is desired short-circuit response time.

Toggle INP1 or EN/UVLO (below $V_{(ENF)}$) or power cycle VS below $V_{(VS_PORF)}$ to reset the latch. At low edge, the timer counter is reset and C_{TMR} is discharged. G1PU pulls up to BST when INP1 is pulled high.

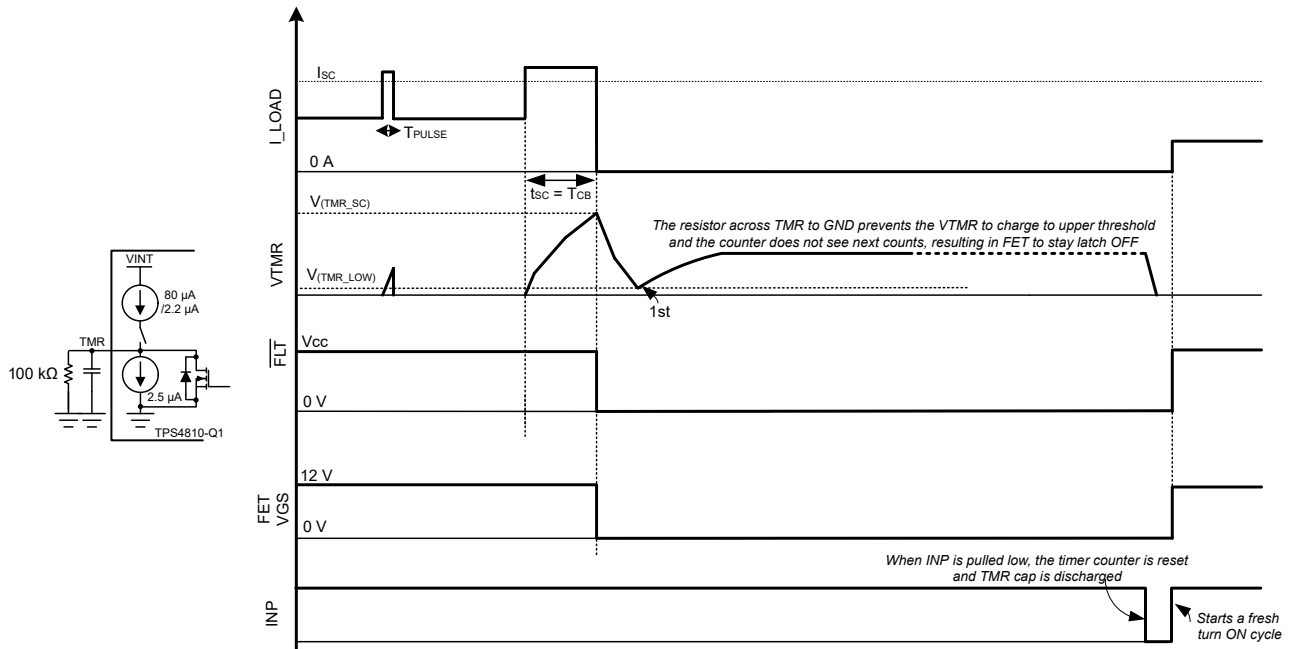


Figure 7-9. Short-Circuit Protection With Latch-Off

7.3.4 Undervoltage Protection (UVLO)

TPS4810-Q1 has an accurate undervoltage protection ($< \pm 2\%$) using EN/UVLO pin providing robust protection. Connect a resistor ladder as shown in Figure 7-10 for undervoltage protection threshold programming.

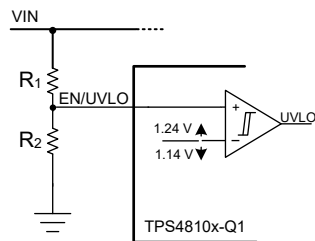


Figure 7-10. Programming Undervoltage Protection

7.3.5 Reverse Polarity Protection

The TPS4810-Q1 devices features integrated reverse polarity protection to protect the device from failing during input and output reverse polarity faults. Reverse polarity faults occur during installation and maintenance of the end equipment. The device is tolerant to reverse polarity voltages down to $-65V$ both on input and on the output.

On the output side, the device can see transient negative voltages during regular operation due to output cable harness inductance kickbacks when the switches are turned OFF. In such systems the output negative voltage level is limited by the output side TVS or a diode.

7.3.6 Short-Circuit Protection Diagnosis (SCP_TEST)

In the safety critical designs, short-circuit protection (SCP) feature and its diagnosis is important.

The TPS48100-Q1 features the diagnosis of the internal short circuit protection. When SCP_TEST is driven low to high then, a voltage is applied internally across the SCP comparator inputs to simulate a short circuit event. The comparator output controls the gate drive (G1PU/G1PD) and also the $\overline{\text{FLT}}$. If the gate drive goes low (with initially being high) and $\overline{\text{FLT}}$ also goes low then it indicates that the SCP is good otherwise it is to be treated as SCP feature is not functional.

If the SCP_TEST feature is not used, then connect SCP_TEST pin to GND.

7.3.7 TPS48100-Q1 as a Simple Gate Driver

Figure 7-11 shows application schematics of TPS48100-Q1 as a simple gate driver in load connect-disconnect switch driving back-to-back FETs topology. The short-circuit protection feature is disabled.

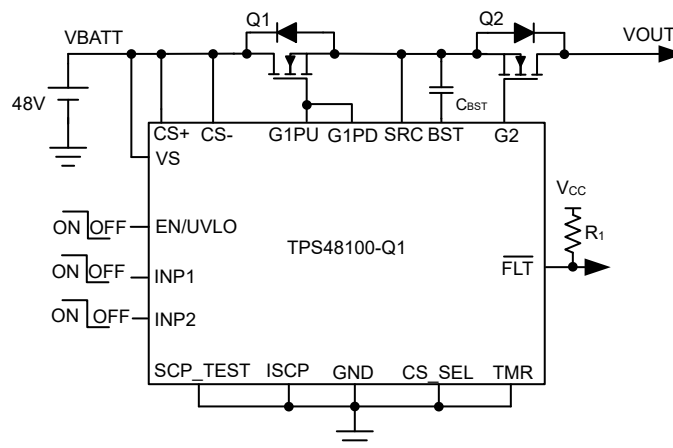


Figure 7-11. TPS48100-Q1 Application Circuit for Simple Gate Driver

7.4 Device Functional Modes

The TPS48100-Q1 has two modes of operation. Active mode and low IQ shutdown mode.

If the EN/UVLO pin voltage is greater than $V_{(ENR)}$ rising threshold, then the device is in active mode. In active state the internal charge pump is enabled, gate drivers, all the protection and diagnostic features are enabled.

If the EN/UVLO voltage is pulled below $V_{(ENF)}$ falling threshold, the device enters into low IQ shutdown mode. In this mode, the charge pump, gate drivers and all the protection features are disabled. The gate drive and external FETs turn OFF. The TPS48100-Q1 consumes low IQ of 1.5 μ A (typical) in this mode.

8 Application and Implementation

Note

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes, as well as validating and testing their design implementation to confirm system functionality.

8.1 Application Information

The TPS48100-Q1 is a 100V, low IQ, smart high side driver with protection and diagnostics. The TPS48100-Q1 device architecture is design to drive and control back-to-back N-Channel MOSFETs independently in common source configuration with separate control inputs (INP1, INP2), which makes TPS48100-Q1 a competitive choice to realize circuit breaker in battery management system (BMS). The strong (2A) GATE drivers enable switching parallel MOSFETs in high current applications, such as circuit breaker in powertrain (DC/DC converter), driving loads in power distribution unit, circuit breaker in 12V, 48V BMS, and so forth.

The TPS48100-Q1 device provides configurable short-circuit protection using ISCP and TMR pins for adjusting the threshold and response time, respectively. Auto-retry and latch-off fault behavior can be configured. By using CS+ and CS- pins, current sensing can be done either by an external sense resistor or by MOSFET VDS sensing. High side or low side current sense resistor configuration is possible by using CS_SEL pin input. The device also features diagnosis of the internal short-circuit comparator using external control on SCP_TEST input.

The following design procedure can be used to select the supporting component values based on the application requirement.

8.2 Typical Application: Circuit Breaker in Battery Management System (BMS) using Low Side Current Sense

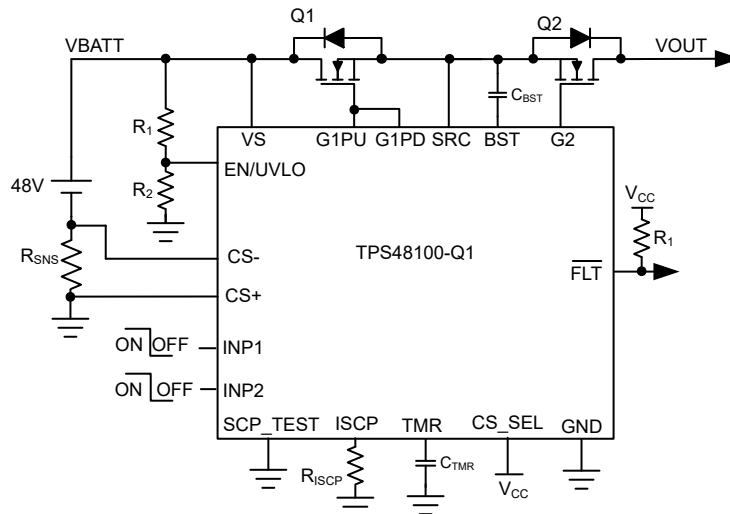


Figure 8-1. Typical Application Schematic: BMS Circuit Breaker With Low Side Current Sense

8.2.1 Design Requirements

The following table shows the design parameters for this application example.

Table 8-1. Design Parameters

PARAMETER	VALUE
Typical input voltage, V_{IN}	48V
Undervoltage lockout set point, $V_{IN_{UVLO}}$	24V
Maximum load current, I_{OUT}	25A

Table 8-1. Design Parameters (continued)

PARAMETER	VALUE
Short-circuit protection threshold, I_{SC}	40A
Short-circuit protection delay (t_{SC})	1ms
Fault response	Auto-retry
Current sensing	Low-side

8.2.2 Detailed Design Procedure

Selection of Current Sense Resistor, R_{SNS}

The recommended range of the overcurrent protection threshold voltage, $V_{(SCP)}$, extends from 30mV to 300mV. Values near the low threshold of 30mV can be affected by the system noise. Values near the upper threshold of 300mV can cause high power dissipation in the current sense resistor. To minimize both the concerns, 40mV is selected as the short-circuit protection threshold voltage. Use the following equation to calculate the current sense resistor, R_{SNS} .

$$R_{SNS} = \frac{V_{(SCP)}}{I_{SC}} \quad (9)$$

The next smaller available sense resistor 1m Ω , 1% is chosen.

To improve signal to noise ratio or for better short-circuit protection accuracy, higher short-circuit protection threshold voltage, $V_{(SCP)}$ can be selected.

Programming the Short-Circuit Protection Threshold – R_{ISCP} Selection

The R_{ISCP} sets the short-circuit protection threshold. Use the following equation to calculate the value.

$$R_{ISCP} (\Omega) = \frac{(I_{SC} \times R_{SNS} - 19 \text{ mV})}{2 \mu\text{A}} \quad (10)$$

To set 30A as short-circuit protection threshold, R_{ISCP} value is calculated to be 5.5k Ω .

Choose the closest available standard value: 5.3k Ω , 1%.

In case where large di/dt is involved, the system and layout parasitic inductances can generate large differential signal voltages between CS+ and CS– pins. This action can trigger false short-circuit protection and nuisance trips in the system. To overcome such scenario, TI suggests to add placeholder for RC filter components across sense resistor (R_{SNS}) and tweak the values during test in the real system. The RC filter components cannot be used in current sense designs by MOSFET VDS sensing to avoid impact on the short-circuit protection response.

Programming the Short-Circuit Protection Delay – C_{TMR} Selection

For the design example under discussion, overcurrent transients are allowed for 1ms duration. This short-circuit protection delay, t_{SC} can be set by selecting appropriate capacitor C_{TMR} from TMR pin to ground. Use the following equation to calculate the value of C_{TMR} to set 1ms for t_{SC} .

$$C_{TMR} = \frac{80 \mu \times t_{SC}}{1.1} = 72.72 \text{ nF} \quad (11)$$

Choose closest available standard value: 82nF, 10%.

Selection of MOSFETs, Q_1 and Q_2

For selecting the MOSFET Q_1 and Q_2 important electrical parameters are the maximum continuous drain current I_D , the maximum drain-to-source voltage $V_{DS(MAX)}$, the maximum drain-to-source voltage $V_{GS(MAX)}$, and the drain-to-source ON-resistance $R_{DS(ON)}$.

The maximum continuous drain current, I_D , rating must exceed the maximum continuous load current.

The maximum drain-to-source voltage, $V_{DS(MAX)}$, must be high enough to withstand the highest voltage seen in the application. Considering 60V as the maximum application voltage, MOSFETs with V_{DS} voltage rating of 80V is designed for this application.

The maximum V_{GS} TPS4810-Q1 can drive is 13V, so a MOSFET with 15V minimum V_{GS} rating must be selected.

To reduce the MOSFET conduction losses, lowest possible $R_{DS(ON)}$ is preferred.

Based on the design requirements, IAUS200N08S5N023 is selected and the ratings are:

- 80V $V_{DS(MAX)}$ and 20V $V_{GS(MAX)}$
- $R_{DS(ON)}$ is 2.3m Ω typical at 10V V_{GS}
- Maximum MOSFET $Q_{g(total)}$ is 110nC

Selection of Bootstrap Capacitor, C_{BST}

The internal charge pump charges the external bootstrap capacitor (connected between BST and SRC pins) with approximately 345 μ A. Use the following equation to calculate the minimum required value of the bootstrap capacitor for driving two IAUS200N08S5N023 MOSFETs.

$$C_{BST} = \frac{Q_{g(total)}}{1V} = 220 \text{ nF} \quad (12)$$

Choose closest available standard value: 220nF, 10%.

Setting the Undervoltage Lockout

The undervoltage lockout (UVLO) can be adjusted using an external voltage divider network of R_1 and R_2 connected between VS, EN/UVLO and GND pins of the device. The values required for setting the undervoltage and overvoltage are calculated by solving [Equation 13](#).

$$V_{(UVLOR)} = \frac{R_2}{(R_1 + R_2)} \times V_{IN_{UVLO}} \quad (13)$$

For minimizing the input current drawn from the power supply, TI recommends to use higher values of resistance for R_1 and R_2 . However, leakage currents due to external active components connected to the resistor string can add error to these calculations. So, the resistor string current, $I(R_{12})$ must be chosen to be 20 times greater than the leakage current of UVLO pin.

From the device electrical specifications, $V_{(UVLOR)} = 1.24V$. From the design requirements, $V_{IN_{UVLO}}$ is 6.5V. To solve the equation, first choose the value of $R_1 = 470k\Omega$ and use [Equation 13](#) to solve for $R_2 = 24.9k\Omega$. Choose the closest standard 1% resistor values: $R_1 = 470k\Omega$, and $R_2 = 24.9k\Omega$.

8.2.3 Application Curves

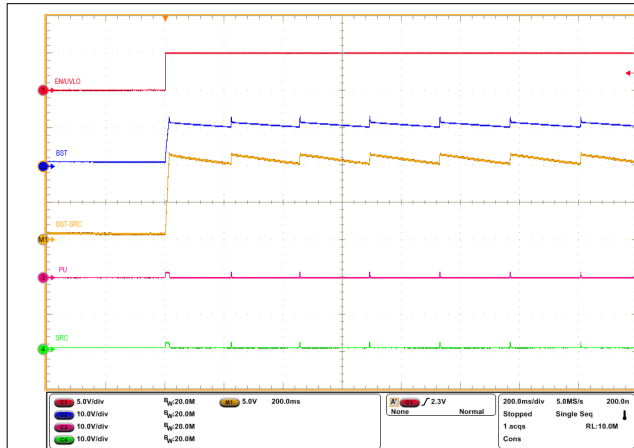


Figure 8-2. Start-Up Profile of Bootstrap Voltage With INP1 = INP2 = GND and $C_{BST} = 470nF$

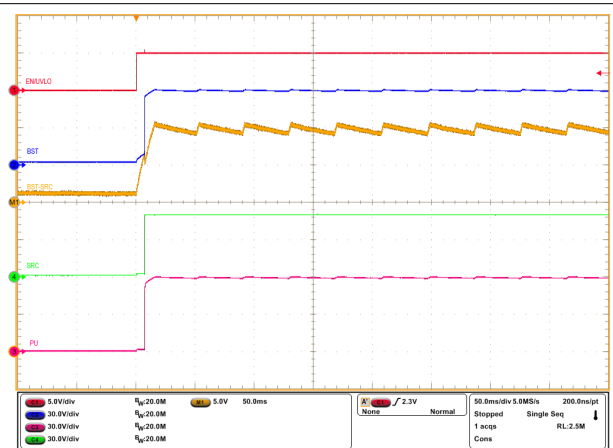


Figure 8-3. Start-Up Profile of Bootstrap Voltage With INP1 = INP2 = HIGH and $C_{BST} = 470nF$

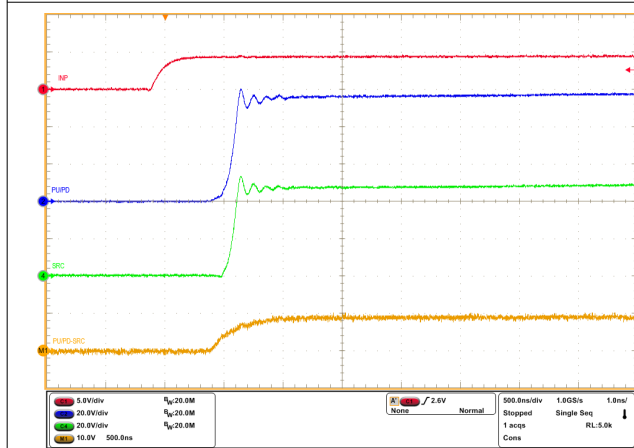


Figure 8-4. Turn-ON Response of TPS48100-Q1 for INP1 -> LOW to HIGH and $C_{BST} = 470nF$

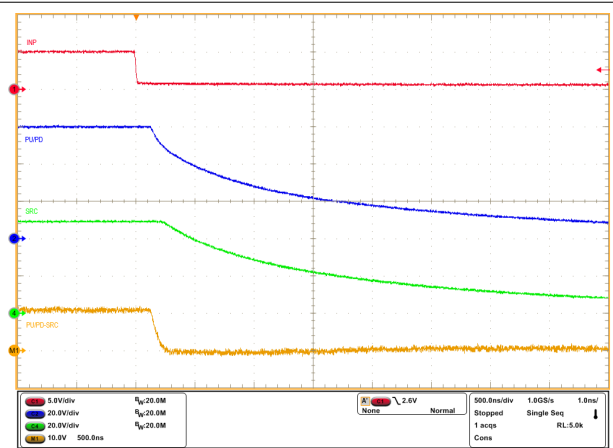


Figure 8-5. Turn-OFF Response of TPS48100-Q1 for INP1 -> HIGH to LOW and $C_{BST} = 470nF$

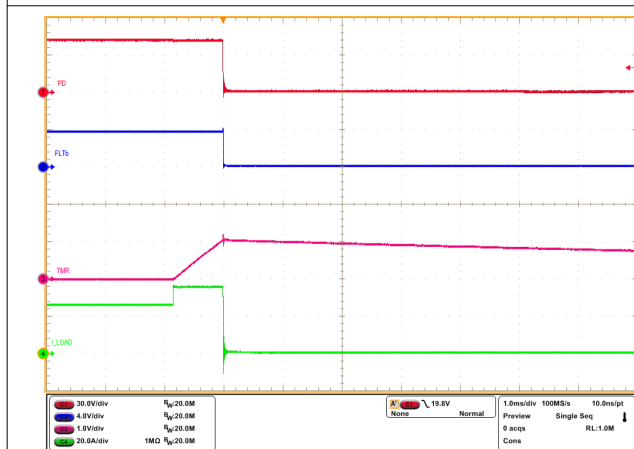


Figure 8-6. Overcurrent Response of TPS48100-Q1 for a Load Step From 25A to 35A With 30A Overcurrent Protection Setting

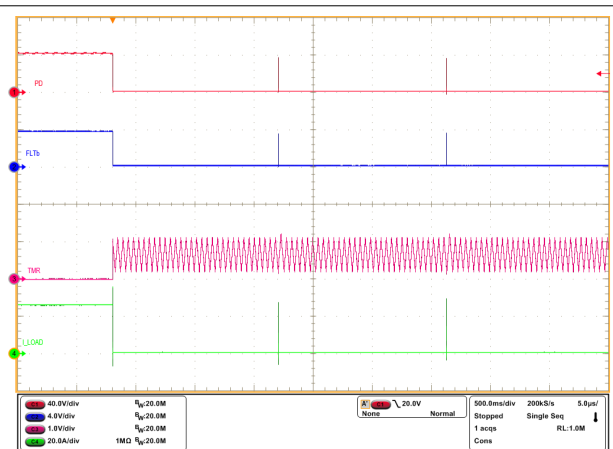


Figure 8-7. Auto-Retry Response of TPS48100-Q1 for an Overcurrent Fault

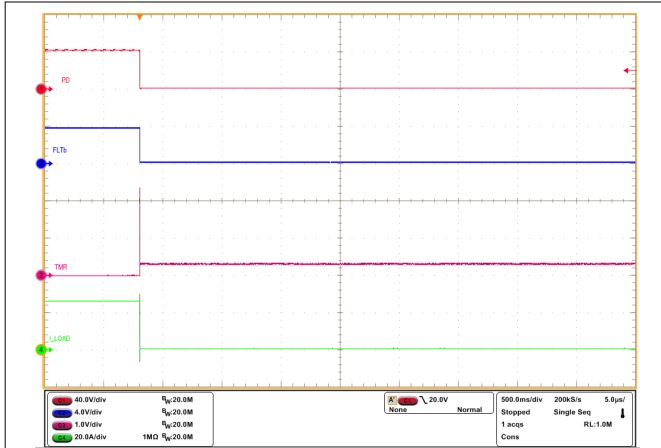


Figure 8-8. Latch-Off Response of TPS4810-Q1 for an Overcurrent Fault

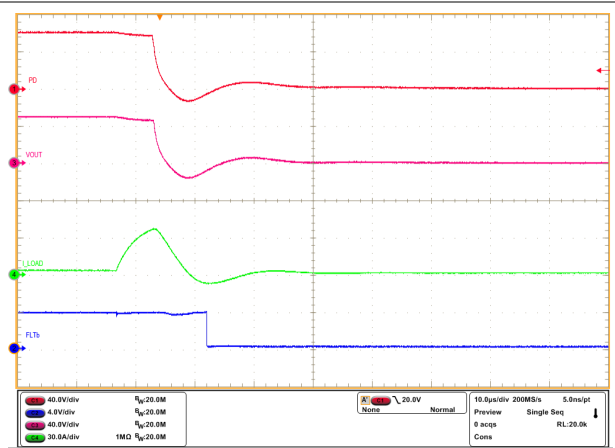


Figure 8-9. Output Short-Circuit Response of TPS4810-Q1 Device

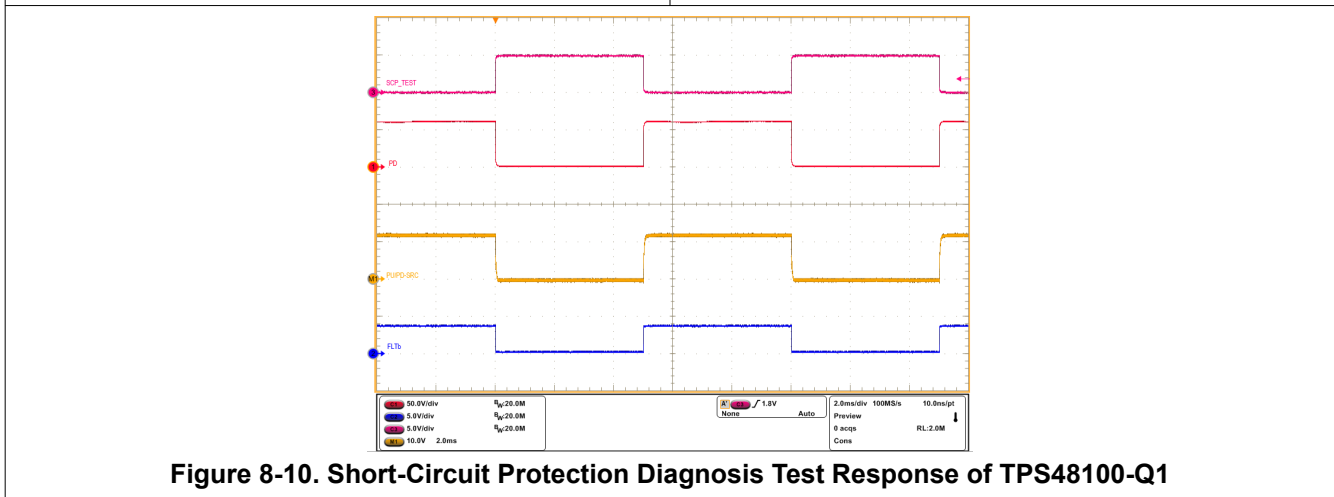


Figure 8-10. Short-Circuit Protection Diagnosis Test Response of TPS4810-Q1

8.3 Power Supply Recommendations

When the external MOSFETs turn-OFF during the conditions such as INP1 control, overcurrent protection causing an interruption of the current flow, the input parasitic line inductance generates a positive voltage spike on the input and output parasitic inductance generates a negative voltage spike on the output. The peak amplitude of voltage spikes (transients) depends on the value of inductance in series to the input or output of the device. These transients can exceed the *Absolute Maximum Ratings* of the device if steps are not taken to address the issue. Typical methods for addressing transients include:

- Use of a TVS diode and input capacitor filter combination across input to and GND to absorb the energy and dampen the positive transients.
- Use of a diode or a TVS diode across the output and GND to absorb negative spikes.

The TPS4810-Q1 gets powered from the VS pin. Voltage at this pin must be maintained above $V_{(VS_PORR)}$ level to specified operation. If the input power supply source is noisy with transients, then TI recommends to place a $R_{VS} - C_{VS}$ filter between the input supply line and VS pin to filter out the supply noise. TI recommends R_{VS} value around 100Ω.

In case where large di/dt is involved, the system and layout parasitic inductances can generate large differential signal voltages between CS+ and CS- pins. This action can trigger false short-circuit protection and nuisance trips in the system. To overcome such scenario, TI suggests to add placeholder for RC filter components across sense resistor (R_{SNS}) and tweak the values during test in the real system. The RC filter components must

not be used in current sense designs by MOSFET VDS sensing to avoid impact on the short-circuit protection response.

The following figure shows the circuit implementation with optional protection components.

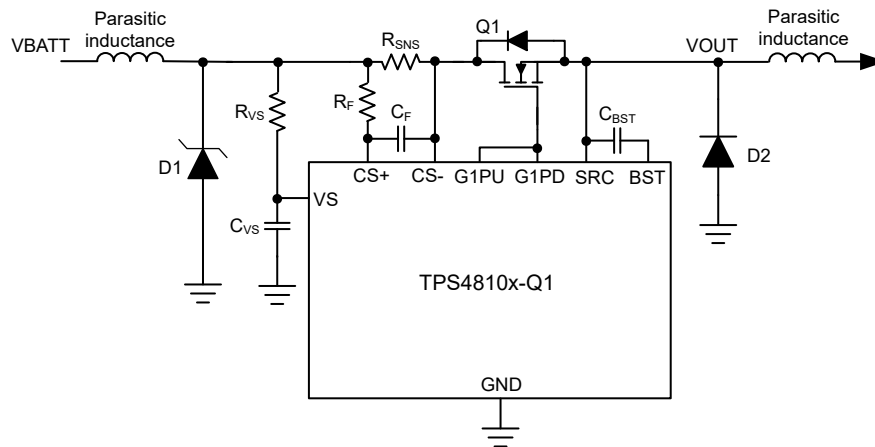


Figure 8-11. Circuit Implementation With Optional Protection Components For TPS4810-Q1

8.4 Layout

8.4.1 Layout Guidelines

- Place the sense resistor (R_{SNS}) close to the TPS4810x-Q1 and then connect R_{SNS} using the Kelvin techniques. Refer to [Choosing the Right Sense Resistor Layout](#) for more information on the Kelvin techniques.
- Choose a 0.1 μ F or higher value ceramic decoupling capacitor between VS terminal and GND for all the applications. Consider adding RC network at the supply pin (VS) of the controller to improve decoupling against the power line disturbances.
- Make the high-current path from the board input to the load, and the return path, parallel and close to each other to minimize loop inductance.
- Place the external MOSFETs close to the controller GATE drive pins (G1PU/PD and G2) such that the GATE of the MOSFETs are close to the controller GATE drive pins and forms a shorter GATE loop. Consider adding a place holder for a resistor in series with the Gate of each external MOSFET to damp high frequency oscillations if need arises.
- Place a TVS diode at the input to clamp the voltage transients during hot-plug and fast turn-off events.
- Place the external boot-strap capacitor close to BST and SRC pins to form very short loop.
- Connect the ground connections for the various components around the TPS4810x-Q1 directly to each other, and to the TPS4810x-Q1 GND, and then connected to the system ground at one point. Do not connect the various component grounds to each other through the high current ground line.

8.4.2 Layout Example

- Top Layer
- Inner Layer GND plane
- Inner Layer PGND plane
- Via to GND plane
- Via to PGND plane

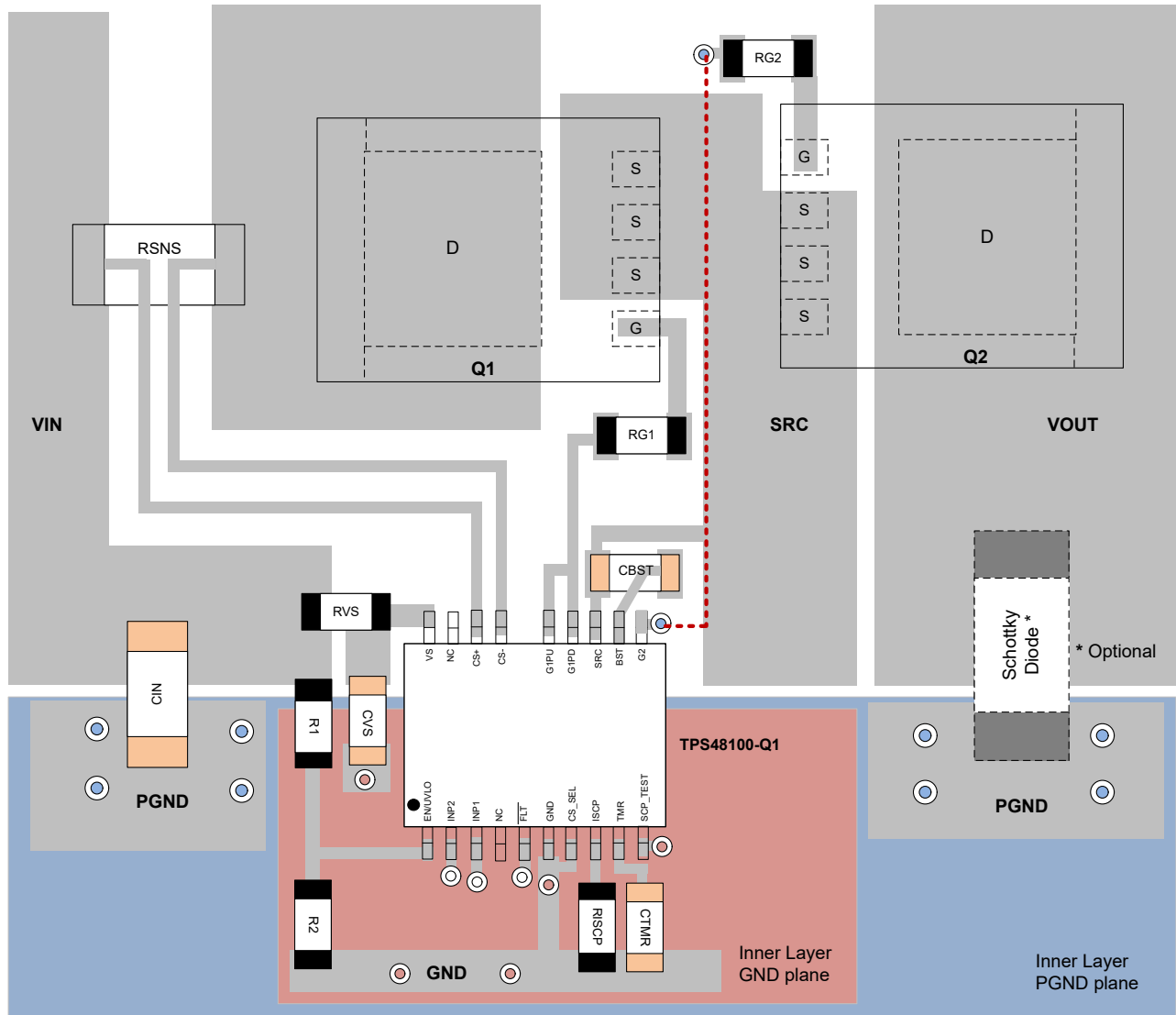


Figure 8-12. Typical PCB Layout Example for TPS4810-Q1 With B2B MOSFETs

9 Device and Documentation Support

9.1 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. Click on *Notifications* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

9.2 Support Resources

[TI E2E™ support forums](#) are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

Linked content is provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

9.3 Trademarks

TI E2E™ is a trademark of Texas Instruments.

All trademarks are the property of their respective owners.

9.4 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

9.5 Glossary

[TI Glossary](#) This glossary lists and explains terms, acronyms, and definitions.

10 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision * (January 2024) to Revision A (December 2024)	Page
• Changed the document status From: <i>Advance Information</i> To: <i>Production Data</i>	1

11 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
PTPS48100QDGXRQ1	ACTIVE	VSSOP	DGX	19	5000	TBD	Call TI	Call TI	-40 to 125		Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSELETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer:The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

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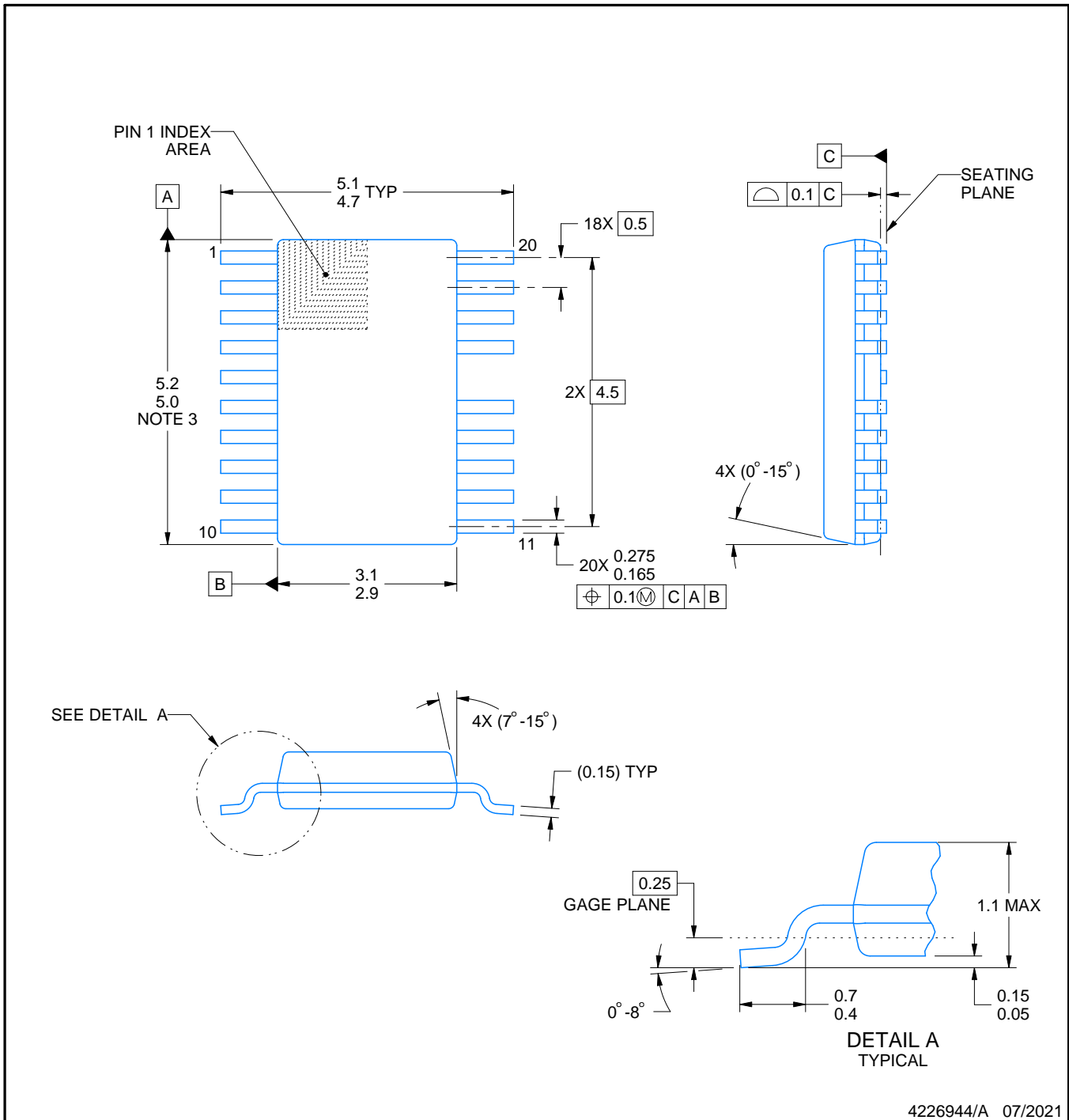
DGX0019A



PACKAGE OUTLINE

VSSOP - 1.1 mm max height

SMALL OUTLINE PACKAGE



4226944/A 07/2021

NOTES:

PowerPAD is a trademark of Texas Instruments.

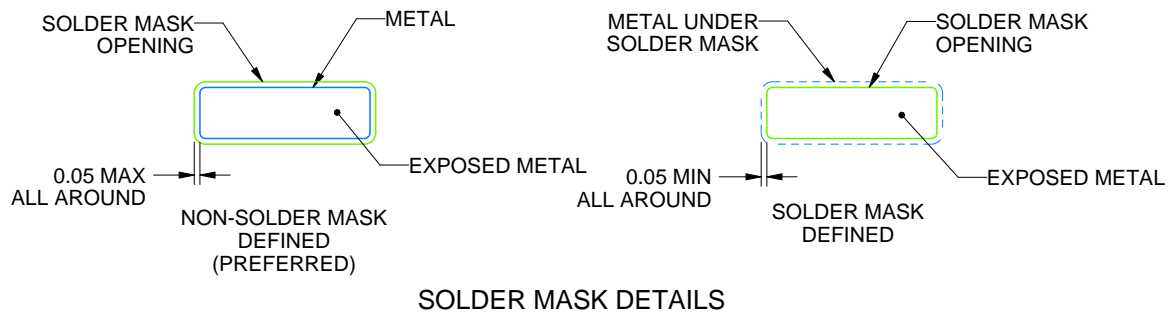
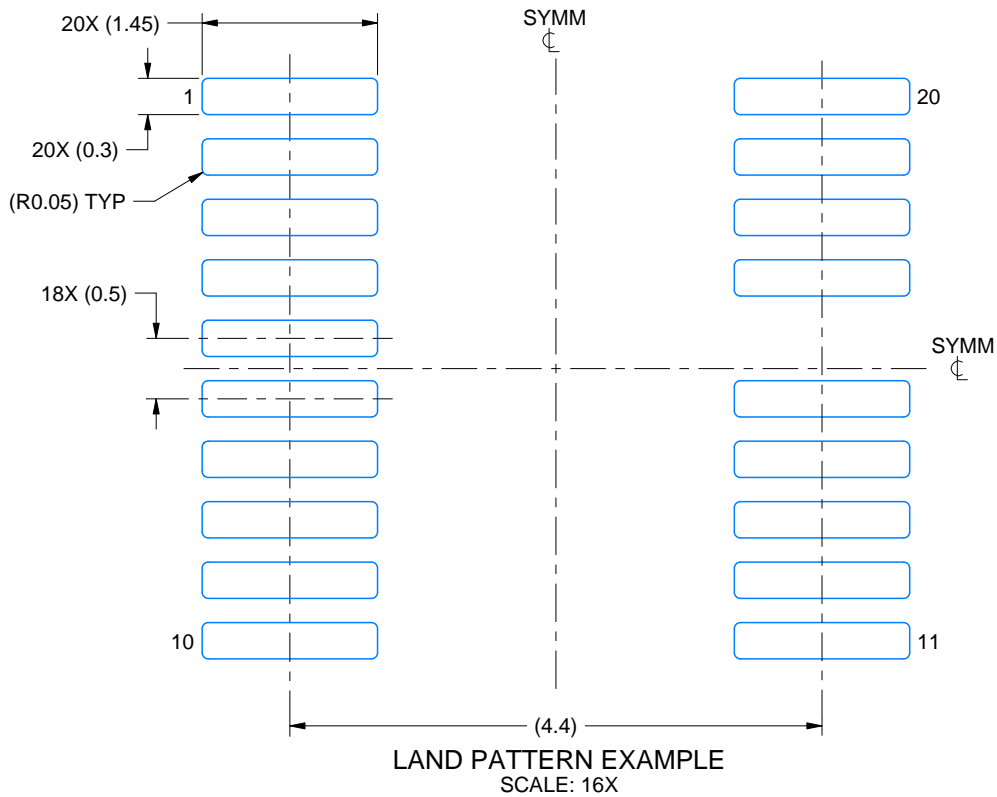
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. No JEDEC registration as of July 2021.
5. Features may differ or may not be present.

EXAMPLE BOARD LAYOUT

DGX0019A

VSSOP - 1.1 mm max height

SMALL OUTLINE PACKAGE



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NOTES: (continued)

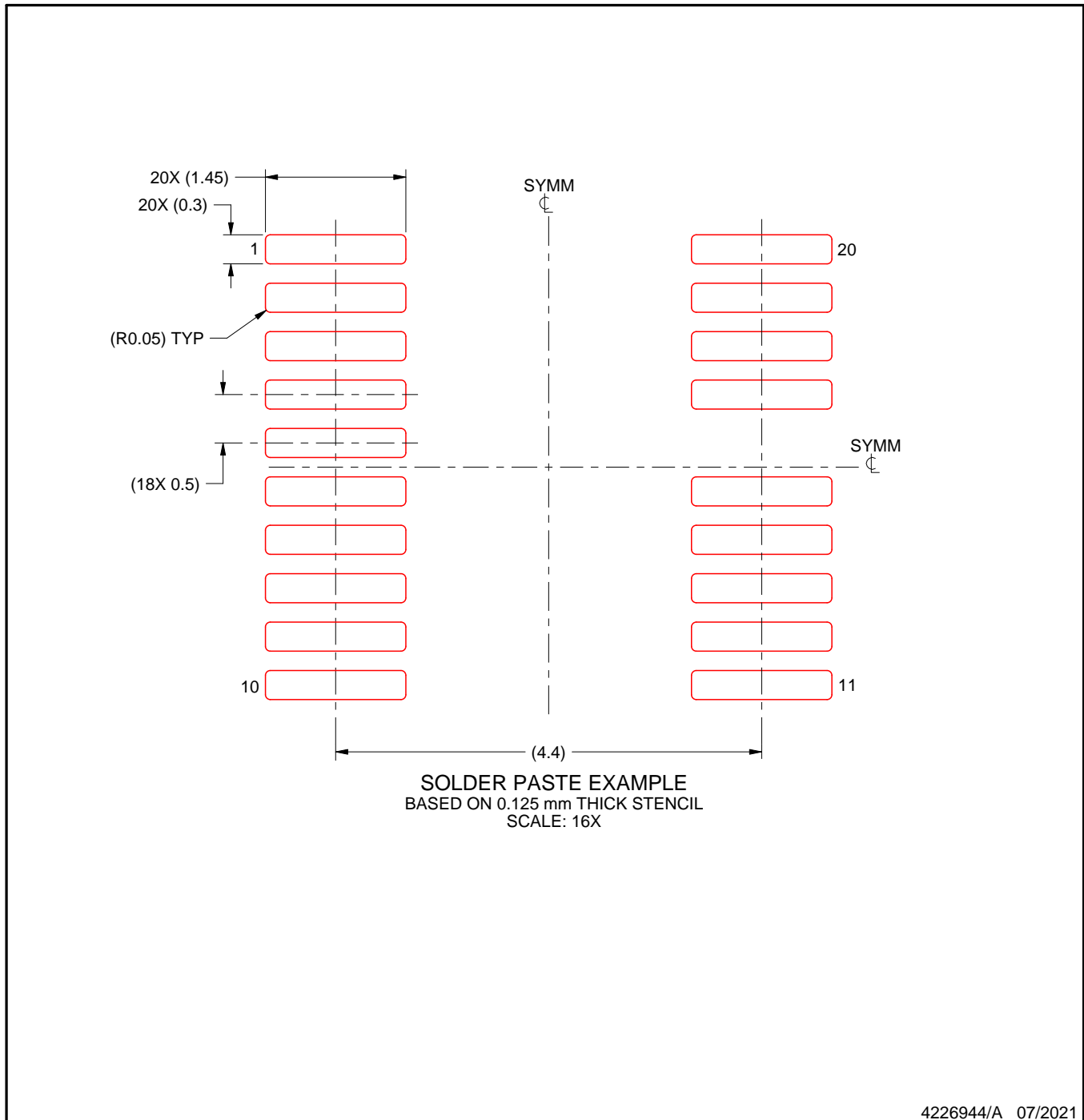
6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.
8. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature numbers SLMA002 (www.ti.com/lit/slma002) and SLMA004 (www.ti.com/lit/slma004).
9. Size of metal pad may vary due to creepage requirement.
10. Vias are optional depending on application, refer to device data sheet. It is recommended that vias under paste be filled, plugged or tented.

EXAMPLE STENCIL DESIGN

DGX0019A

VSSOP - 1.1 mm max height

SMALL OUTLINE PACKAGE



NOTES: (continued)

11. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
12. Board assembly site may have different recommendations for stencil design.

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